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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/590,527	06/08/2000	Salman Akram	4101US (99-0572)	1156
7590	10/04/2004		EXAMINER	
Brick G Power Trask Britt PO Box 2550 Salt Lake City, UT 84110				MITCHELL, JAMES M
			ART UNIT	PAPER NUMBER
			2813	

DATE MAILED: 10/04/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	09/590,527	AKRAM, SALMAN	
	<b>Examiner</b>	<b>Art Unit</b>	
	James M. Mitchell	2813	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --  
**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

- 1) Responsive to communication(s) filed on 29 June 2004.
- 2a) This action is FINAL.                    2b) This action is non-final.
- 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

- 4) Claim(s) 38-69 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) Claim(s) \_\_\_\_\_ is/are allowed.
- 6) Claim(s) 38-69 is/are rejected.
- 7) Claim(s) \_\_\_\_\_ is/are objected to.
- 8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

- 9) The specification is objected to by the Examiner.
- 10) The drawing(s) filed on \_\_\_\_\_ is/are: a) accepted or b) objected to by the Examiner.  
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
  - a) All    b) Some \* c) None of:
    1. Certified copies of the priority documents have been received.
    2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
    3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

- 1) Notice of References Cited (PTO-892)
- 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  
 Paper No(s)/Mail Date 6/29/04.
- 4) Interview Summary (PTO-413)  
 Paper No(s)/Mail Date. \_\_\_\_\_.
- 5) Notice of Informal Patent Application (PTO-152)
- 6) Other: \_\_\_\_\_.

## DETAILED ACTION

This office action is in response to applicant's amendment filed June 29, 2004.

### ***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 38-41, 44-55, 58-63 and 66-69 are rejected under 35 U.S.C. 103(a) as being unpatentable over applicant's admitted prior art (APA) in combination with Hashimoto (US 6,410,366).

APA (FIG 1 and 2; Spec. Page 2, 3, 4 & 13) discloses an assembly, test substrate and a CSP, semiconductor device that is a die (200) comprising an inherent substrate formed from a wafer or chip scale package and contact pad (202) being arranged in at least one substantially linear relationship positioned at or proximate a centerline of said substrate and being configured to temporary communicate with corresponding test pads (230) of a test substrate (210) upon disposing said substrate face-down over said test substrate; with at least one conductive structure (220) disposed between said test substrate and said semiconductor device with said test substrate inherently in a plane (via X-axis going through middle of substrate, 214).

APA does not appear to disclose at least one elongated stabilizer protruding from said surface wherein said stabilizer is dielectric that is at least a semisolid that is

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comprised of a plurality of superimposed, contiguous, mutually adhered layers of the same material, said at least one stabilizer being configured to at least partially stabilize an orientation of the semiconductor device upon disposal thereof face-down over said test substrate, wherein said stabilizer protrudes from said surface at most a distance between a plane of said surface of said substrate and a plane of a surface of said test substrate upon disposing said substrate face-down over said test substrate, at least one said stabilizer positioned to be located proximate a corner of said surface and has a cross-sectional plan of an quadrilateral, or said stabilizer being secured to said surface of said test substrate or that the stabilizer is elongated in a direction parallel to a plane in which said substrate is located.

However Hashimoto (Fig 1a-c; Col. 5, Lines 34-58) utilizes at least one elongated stabilizer comprised of the same material via dielectric and insulating material (11, 21; Col. 5, Lines 41-44 & Col. 7, Lines 5-7) protruding from said surface wherein said stabilizer (via both portions 11 & 21) is dielectric that is at least a semisolid and that is comprised of a plurality (11, 21) of superimposed are contiguous, mutually adhered layers (Col. 4, Lines 22-26), said at least one stabilizer being configured to at least partially stabilize ("support"; i.e. prevents collapse of chip at area where stabilizers is in contact) an orientation of the semiconductor device upon disposal thereof face-down over a substrate; wherein said stabilizer protrudes from said surface at most a distance between a plane of said surface of said substrate and a plane of a surface of said substrate upon disposing said substrate face-down over substrate, and at least one said stabilizer positioned to be located proximate a corner of said surface (Fig 1A ) and has a

cross-sectional plan of a quadrilateral (i.e. cyclic quadrilateral); said stabilizer secured to said surface of said substrate and the stabilizer is elongated (i.e. stabilizer, 11&21, stretched along x-axis and therefore elongated) in a direction parallel to a plane in which said substrate is located (i.e. substrate in an x-axis plane).

It would have been obvious to one of ordinary skill in the art to incorporate the stabilizers of Hashimoto that are comprised of a plurality of superimposed, contiguous, mutually adhered layers with the test substrate of APA in order to provide support as taught by Hashimoto (Col. 5, Line 53).

Furthermore with respect to shape of stabilizers, it would have been an obvious matter of design choice bounded by well known manufacturing constraints and ascertainable by routine experimentation and optimization to vary the shape of the particular dimensions of the stabilizer, because applicant has not disclosed that the dimensions are for a particular unobvious purpose, produce an unexpected result, or are otherwise critical as supported by applicant's specification page 13 (stabilizers may be circular or alternatively rectangular or triangular), and it appears *prima facie* that the process would possess utility using another dimension. Indeed, it has been held that mere dimensional limitations are *prima facie* obvious absent a disclosure that the limitations are for a particular unobvious purpose, produce an unexpected result, or are otherwise critical. See, for example, *In re Rose*, 220 F.2d 459, 105 USPQ 237 (CCPA 1955); *In re Rinehart*, 531 F.2d 1048, 189 USPQ 143 (CCPA 1976); *Gardner v. TEC Systems, Inc.*, 725 F.2d 1338, 220 USPQ 777 (Fed. Cir. 1984), cert. denied, 469 U.S. 830, 225 USPQ 232 (1984); *In re Dailey*, 357 F.2d 669, 149 USPQ 47 (CCPA 1966).

Claims 42, 43, 56, 57, 64 and 65 are rejected under 35 U.S.C. 103(a) as being unpatentable over applicant's admitted prior art (APA) and Hashimoto (US 6,410,366) as applied to claims 38, 53 and 60 and further in combination with Sasaki (JP 402210329).

Neither APA nor Hashimoto appears to disclose that the stabilizers are photopolymer, however, Sasaki (Fig 1) utilizes a photopolymer (16).

It would have been obvious to one of ordinary skill in the art to form the stabilizer of APA and Hashimoto from a photopolymer in order to provide an insulating material for the stabilizer as required by Hashimoto (Col. 5, Lines 41-44; Col. 7, Lines 5-7) and that provides uniformity of gap as taught by Sasaki (English Constitution).

### ***Response to Arguments***

Applicant's arguments filed January 29, 2004 have been fully considered but they are not persuasive.

Applicant argues several points: 1) Hashimoto does not teach a test substrate, 2) the bumps of Hashimoto are not mutually adhered; 3: the prior art fails to teach stabilizers elongated in a direction parallel to a plane in which the substrate is located; 4) the prior art does not show a semiconductor wafer with stabilizers; 5) there is no teaching of a chip scale package with stabilizers; 6) no motivation to replace a permanent substrate with a temporary substrate; 7) Hashimoto teachings are only limited to a carrier substrate; and 8) Sasaki only includes a single layer.

In response:

1 & 6) examiner re-emphasizes that Hashimoto was not relied on to show a test substrate, but for its teaching of stabilizers, the primary reference which was APA, contained an explicit teaching of a test substrate, 210 (App. Spec. Page 3). Examiner has made no suggestion to replace a temporary substrate with a permanent, thus applicant's argument is deemed moot;

2) Hashimoto explicitly states that the bumps are bonded together (Col. 4, Lines 22-26);

3) the plain and ordinary meaning of elongate only requires that material extend/stretch out over a length, as such, stabilizers/bumps that extend horizontally and/or laterally are elongated;

4) a die/ chip comprises a thin slice of semiconductor material and therefore is within the broad scope of the plain and ordinary meaning of a wafer;

5) a bare chip with attached electrodes and stabilizers and a chip scale package are not mutually exclusive, furthermore because applicant's claim recites comprising language there is no limit to how little (none) or much the chip has to be further protected (i.e. cover, encapsulant etc.). Likewise, applicant's specification Page 2, recites that the semiconductor device includes CSP, which is illustrated in Fig 1;

7) applicant's suggestion that Hashimoto's teachings are limited to a carrier substrate amounts to an argument that APA and Hashimoto are nonanalogous, however, since both APA and Hashimoto deal with placing chip/die on a substrate (test, permanent or otherwise) the references are deemed to be in the same field and in

addition stabilizers/spacers are used in the art on both test and permanent substrates (i.e. Uchida and Chang). See *In re Oetiker*, 977 F.2d 1443, 24 USPQ2d 1443 (Fed. Cir. 1992);

8) Sasaki was only relied to teach a particular type of insulating material therefore how many layers it may or may not have is not pertinent to its disclosure.

In light of examiner's responses, *supra*, applicant's arguments are deemed unpersuasive and the present rejection maintained.

### ***Conclusion***

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Chang (U.S. 5,206,585) and Uchida (U.S. 5,684,677).

The pertinent art discloses the use of stabilizers/ spacers on either a temporary or permanent substrate.

### ***Conclusion***

**THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any

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extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to James M. Mitchell whose telephone number is (571) 272-1931. The examiner can normally be reached on M-F 8:00-4:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



JMM  
September 16, 2004.



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